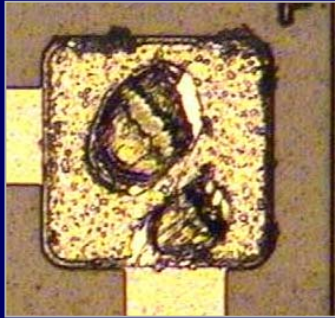


Reducing False Defects: Debris and Edge Excursions

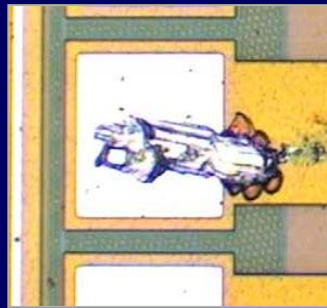
Rajiv Roy, August Technology
SW Test Workshop
June 8, 2005



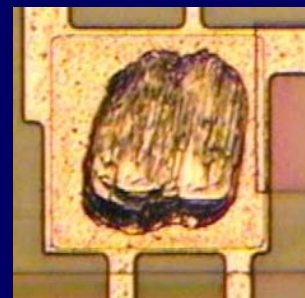
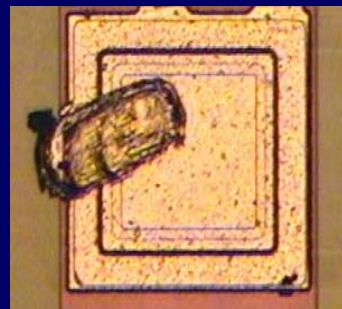
Post-probe : Typical Process Defects Detected



- Probe mark too big
- Probe mark too small
- Missing probe mark



- Pad discoloration
- Probe mark location
- Probe mark too close to edge

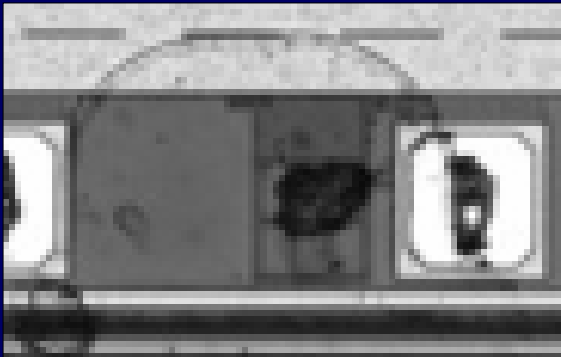


Probe Mark Inspection

- Rectangular bond-pads
- Bond pad corrosion
- Probe mark area and location metrology
- Probe mark debris filter – size
- Probe mark debris filter – edge debris
- Real-time classification of probe mark defects
- Non-rectangular bond-pad
- Separate image save
- Auto-bond pad location

Why Automate Inspection?

System can find defects like these missed by operators:



Debris and stain



Passivation on pad

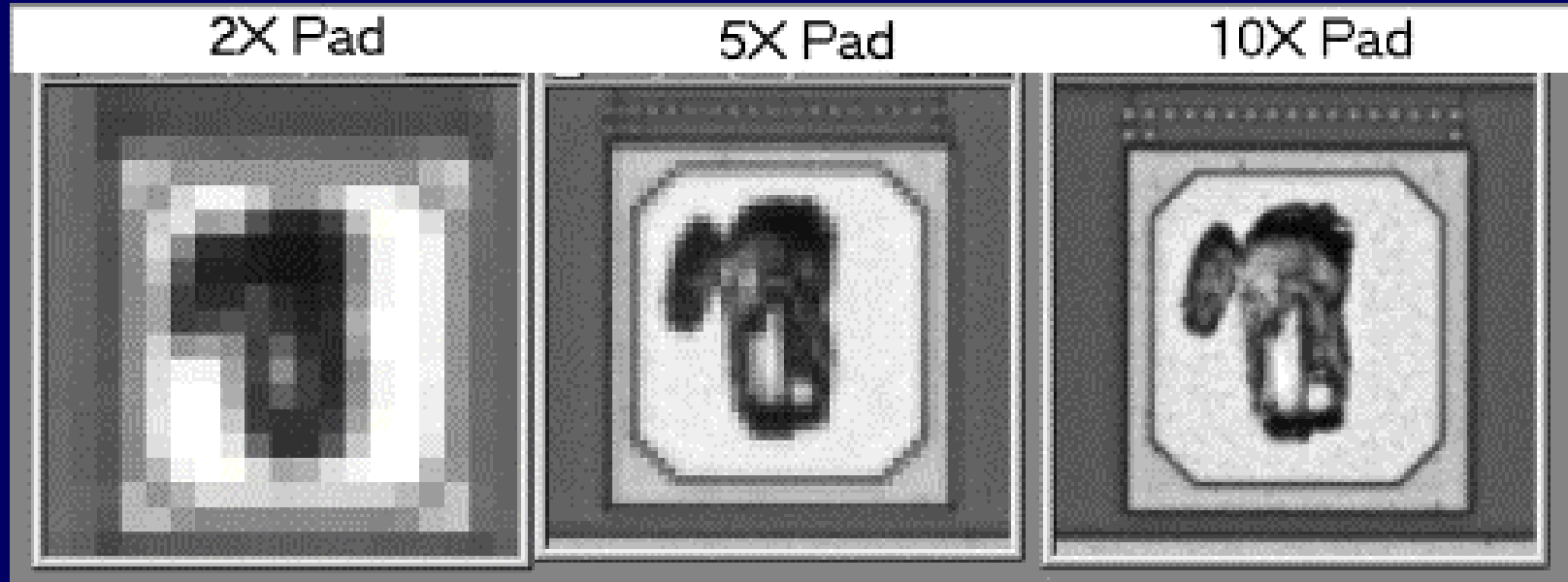


Excess metal
flake near pad

The Challenge of Automated Probe Mark Inspection

- To make inspection affordable
 - >15wph or higher throughput needed
 - Better than 1 μ m resolution needed for distinguishing true from false defects

See More at Higher Resolutions



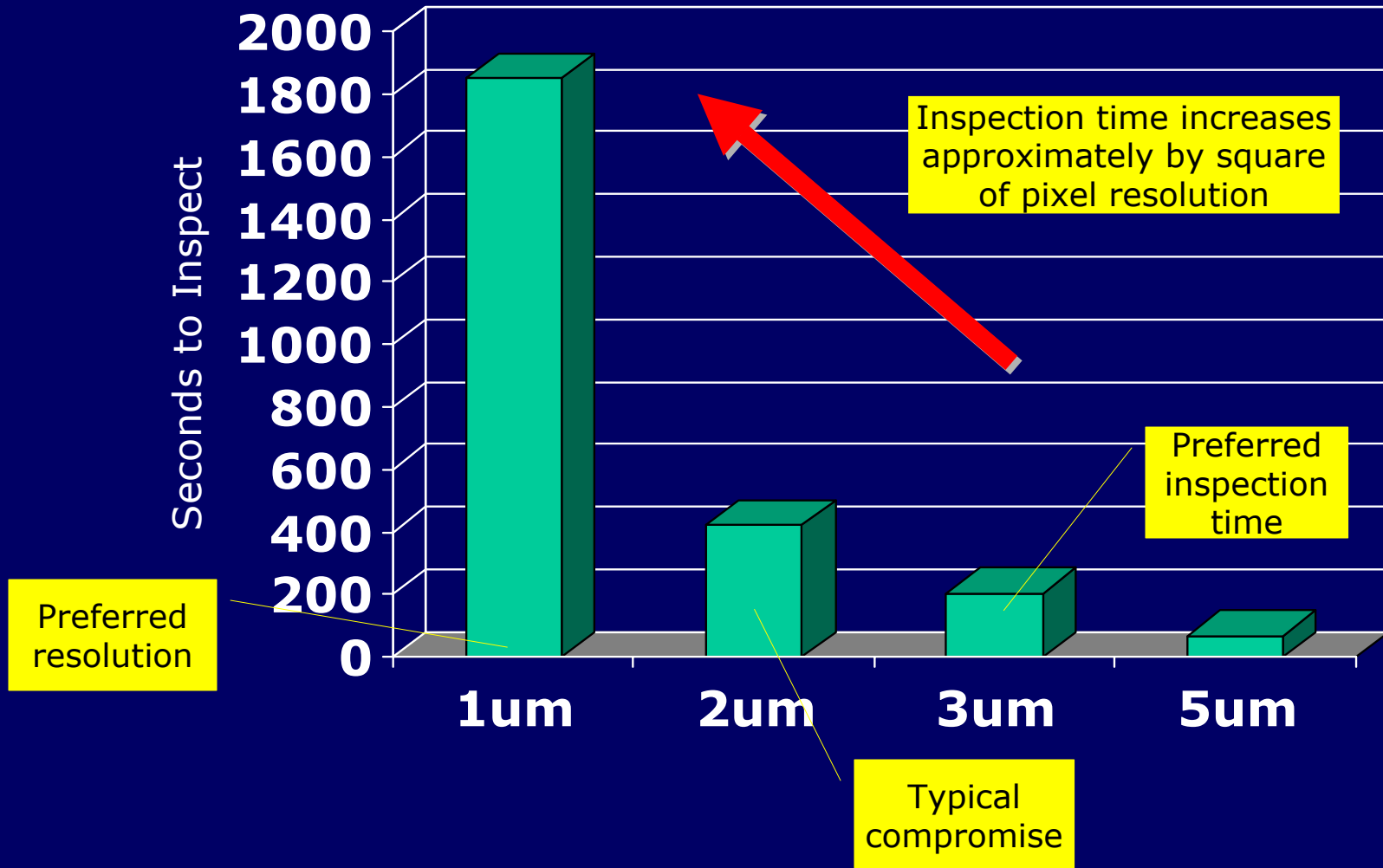
5µm

2µm

1µm

....but takes more inspection time

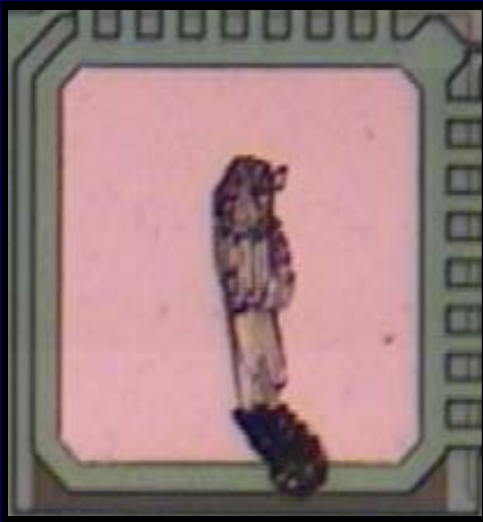
Throughput vs. Resolution



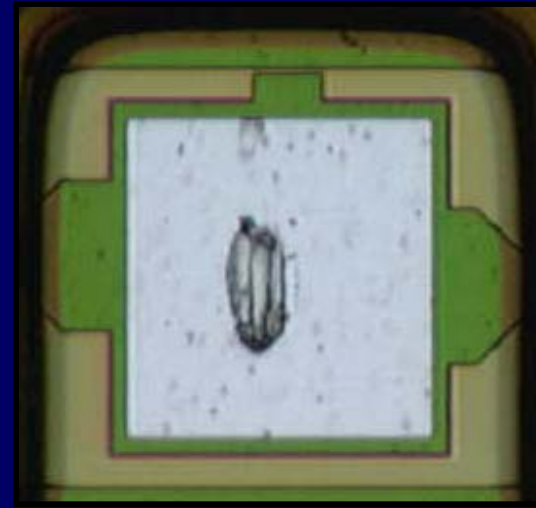
The Probe Mark Debris Challenge

- Debris is:
 - A natural by-product of the probing process
 - Considered non-critical to device functionality
- Automatic probe mark inspection systems have difficulty differentiating between defects and debris.

..... a source of false defects

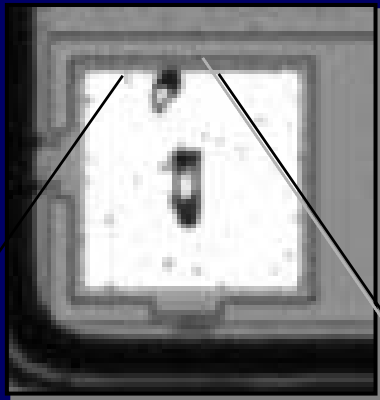


Aluminum slag/debris –
mistaken for probe mark too big



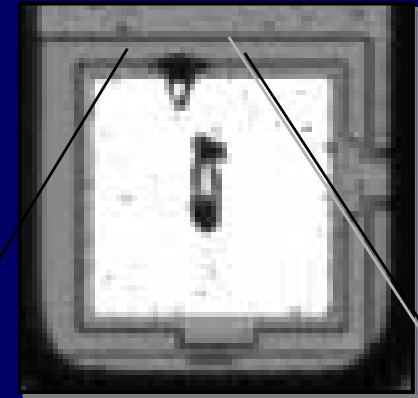
Edge debris – small/faint –
mistaken for edge excursion

The Specific Challenge of Edge Excursions



False edge defect at 5X

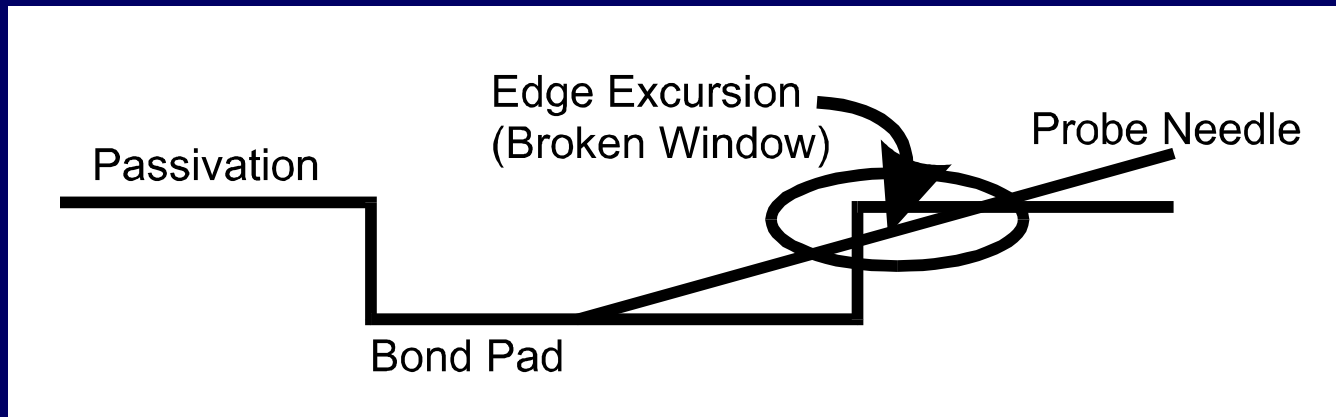
Distinguishing between



True edge defect at 5X

Cause of Edge Excursion

- ❗ If probe needles and bond pad are not aligned properly, needles penetrate the edge of the passivation layers and cause a defect
- ❗ This defect is known as edge excursion or broken passivation



Rogues Gallery: Images of False vs. True Defects

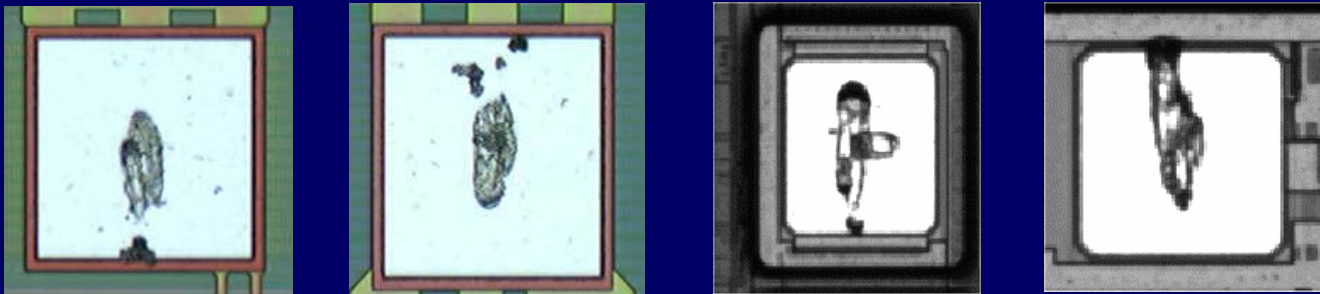
- **Real edge excursion – systems can detect**



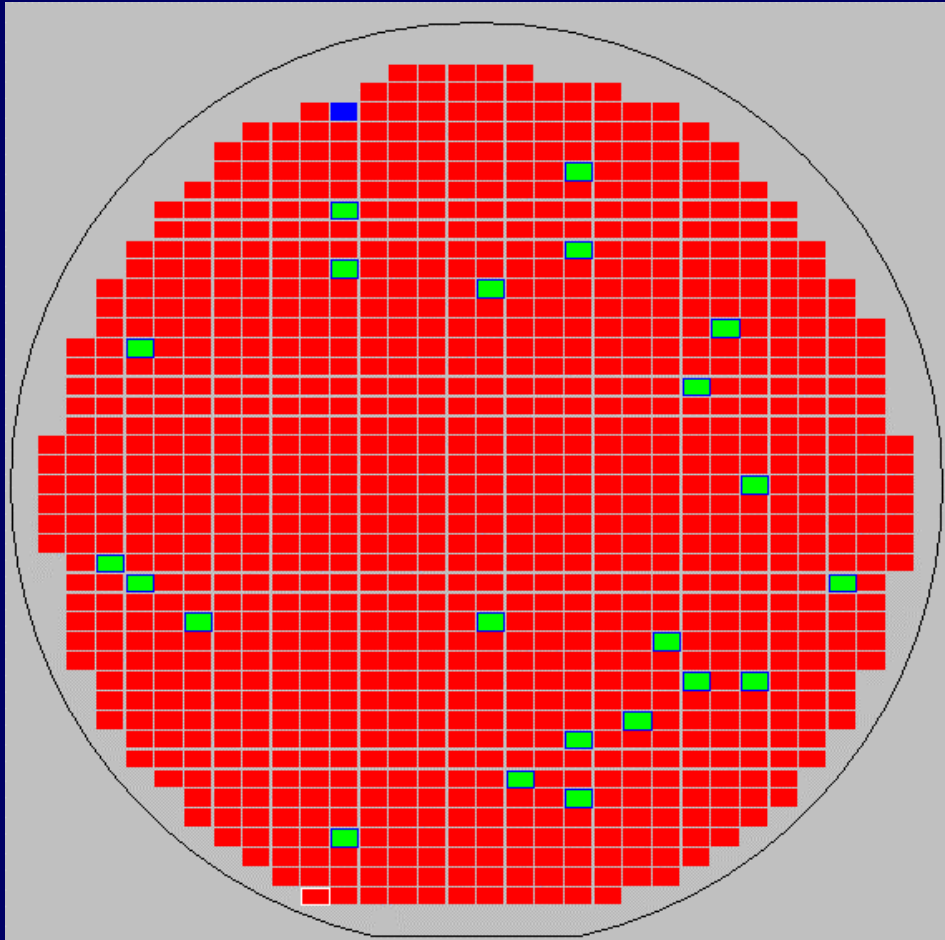
- **Real edge excursion – systems struggle to detect**



- **Edge debris – systems detect but are false defects**



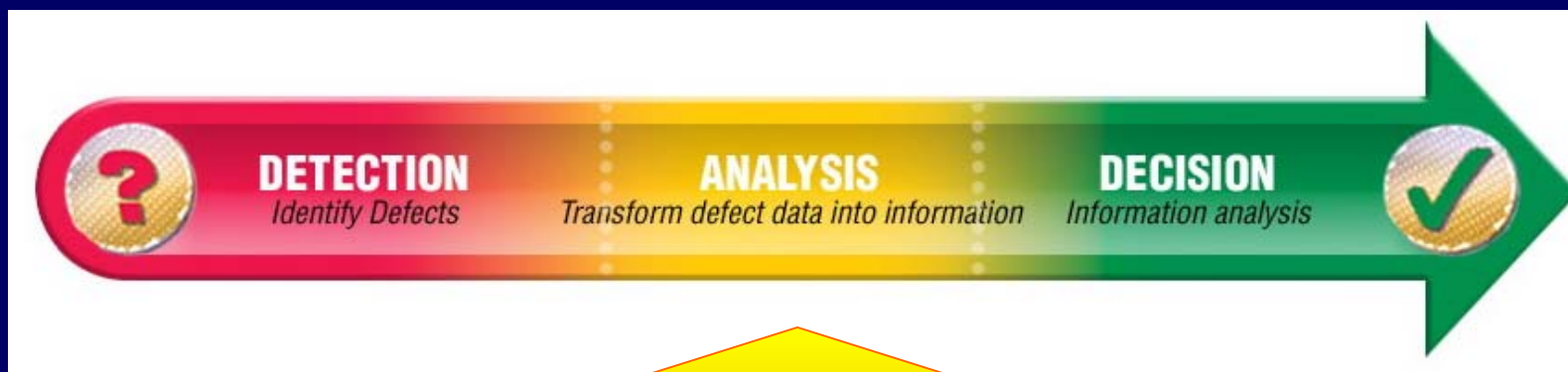
The Effect of Simply Detecting "Defects" (Anomalies)



Inspection Results: 5x	Inspection Time:	5 minutes
	Total number of defects:	14400
	Approximate Review Time	2 hours 20 minutes

- **Fast inspection**
- **Unacceptable review time**

Detection to Decision for Probe Mark Inspection



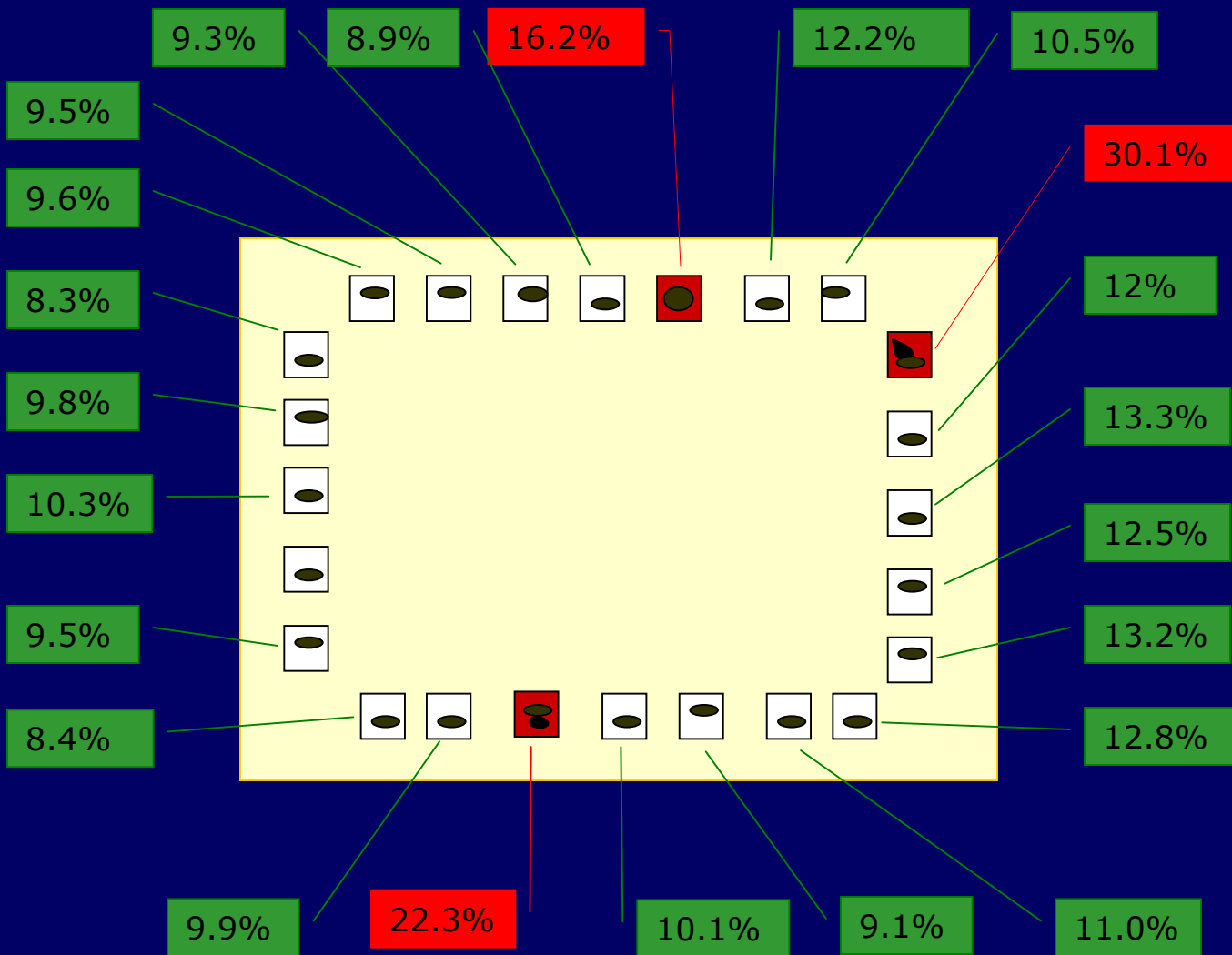
- Statistical Probe Mark Area Filter
- Debris Filter for Edge

Statistical Probe Mark Area Filter

Assumptions Made:

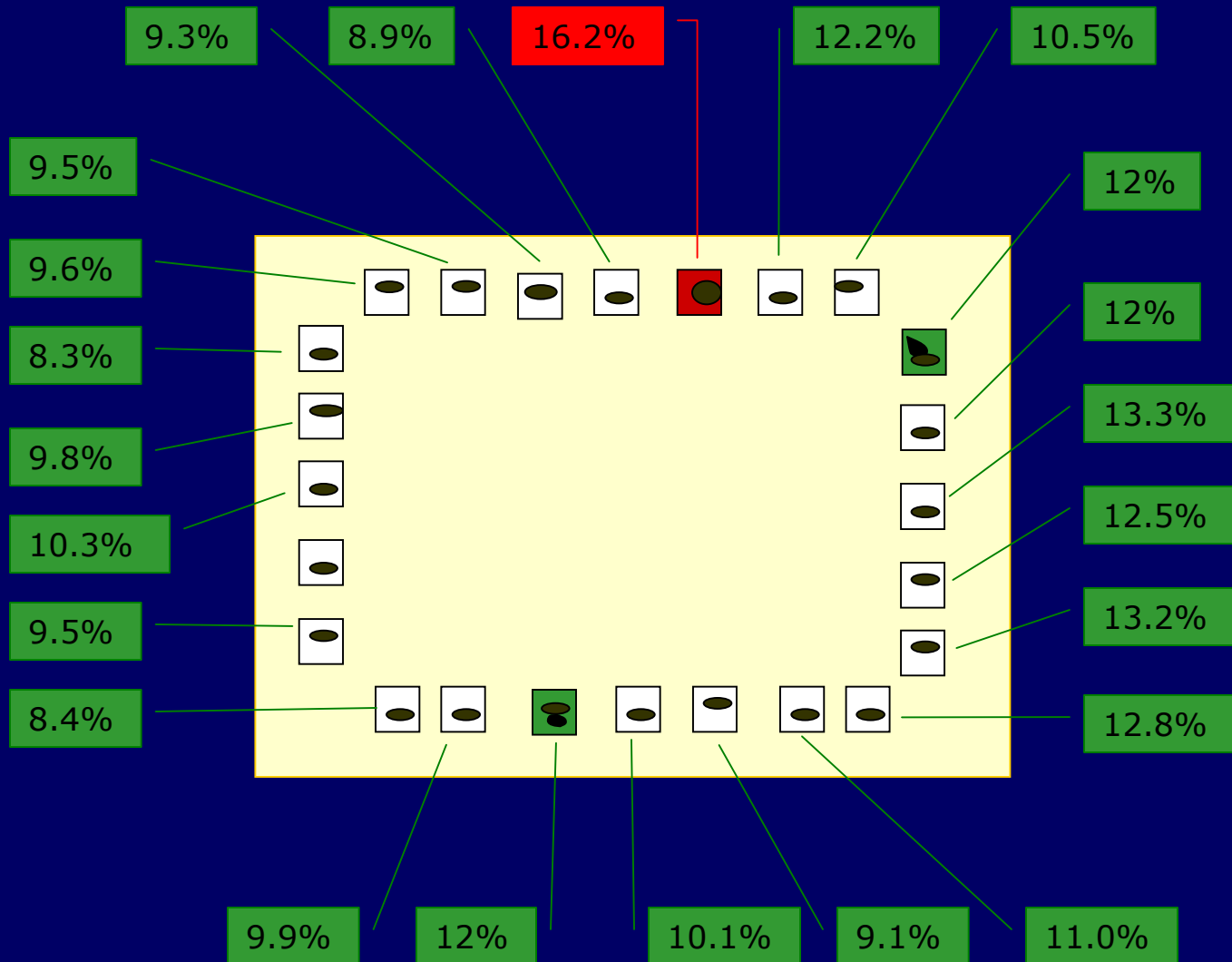
- All bond pads on one die have been subjected to the same number of touchdowns
- Actual probe damage area will not differ in a statistically significant manner within one die

Probe Mark Area Inspection Without Filter



Max. area = 15%
Pad areas greater than max. area fail

Probe Mark Area Inspection With Area Filter

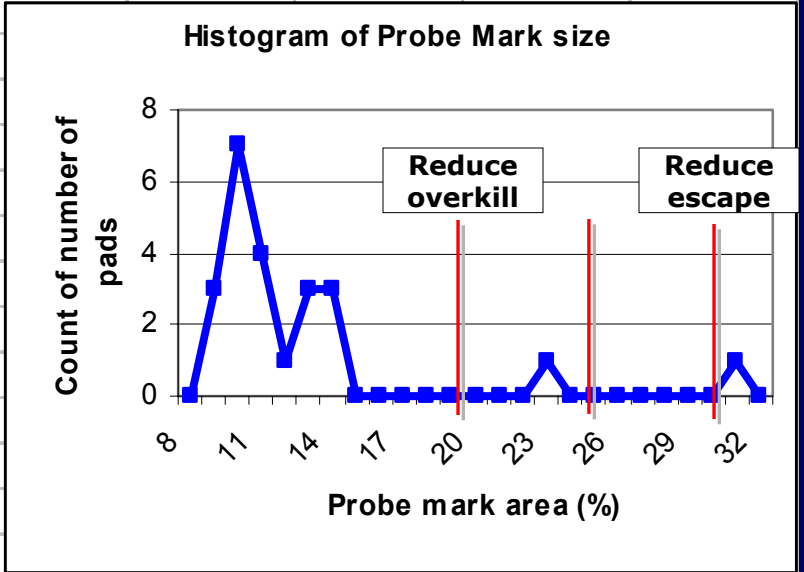


Max. area = 15%
Pad areas greater than max. area fail

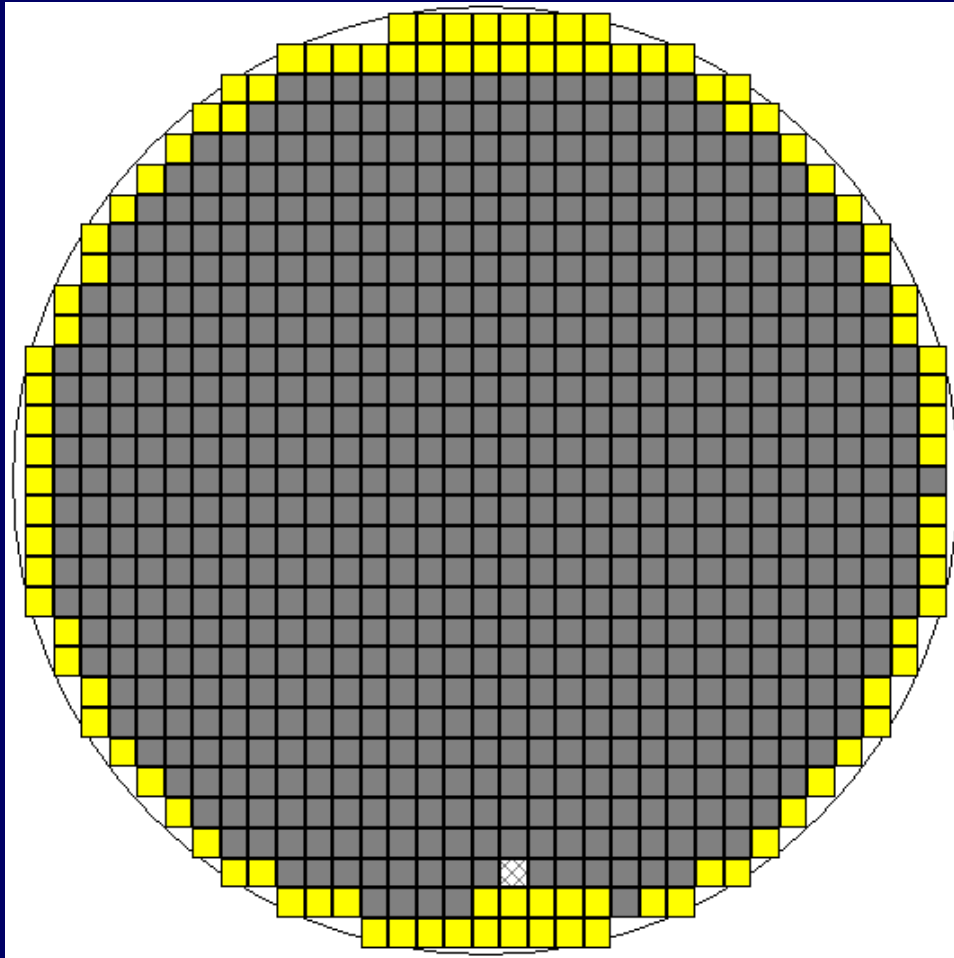
Standard Deviations vs. Performance

Bond Pad	No Filter	2 σ Filter	3 σ Filter	4 σ Filter
1	9.60	9.60	9.60	9.60
2	9.50	9.50	9.50	9.50
3	9.30	9.30	9.30	9.30
4	8.90	8.90	8.90	8.90
5	16.20	16.20	16.20	16.20
6	12.20	12.20	12.20	12.20
7	10.50	10.50	10.50	10.50
8	30.10	11.99	11.99	30.10
9	12.00	12.00	12.00	12.00
10	13.30	13.30	13.30	13.30
11	12.50	12.50	12.50	12.50
12	13.20	13.20	13.20	13.20
13	12.80	12.80	12.80	12.80
14	11.00	11.00	11.00	11.00
15	9.10	9.10	9.10	9.10
16	10.10	10.10	10.10	10.10
17	22.30	11.99	22.30	22.30
18	9.90	9.90	9.90	9.90
19	8.40	8.40	8.40	8.40
20	9.50	9.50	9.50	9.50
21	10.30	10.30	10.30	10.30
22	9.80	9.80	9.80	9.80

Average PM Damage %	11.9913
Std Deviation of PM Damage %	4.900919
Debris Filter 2 Std Deviations	21.79314
Debris Filter 3 Std Deviations	26.69406
Debris Filter 4 Std Deviations	31.59498

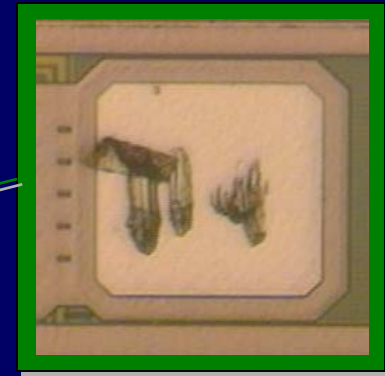
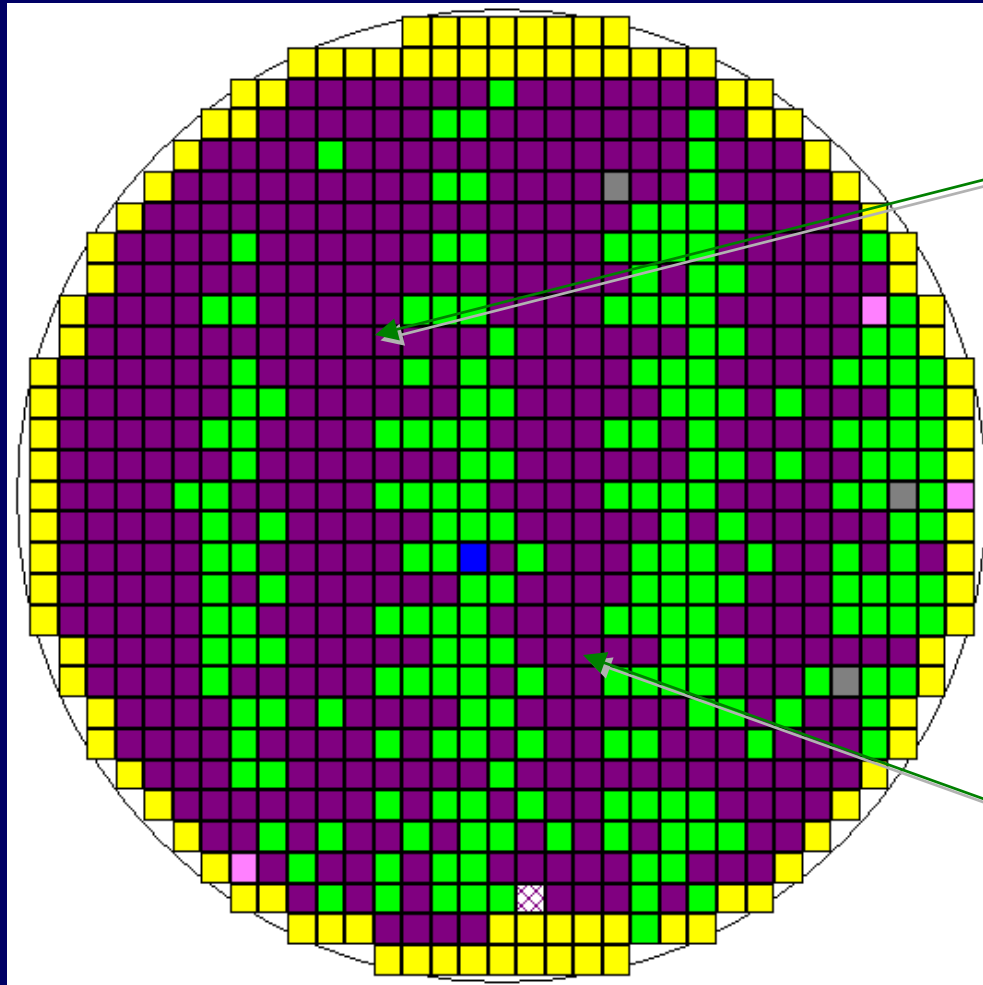


Parameters for Area Filter Test

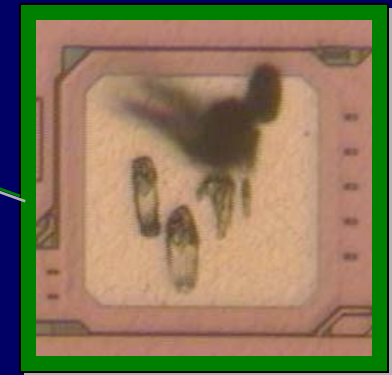


Wafer size:	8-inch
Inspected die:	713
Die size:	5897um x 6349um
Pads/die:	38
Max. area:	25%
Std. Devs:	1.1

Defect Map Without Area Filter



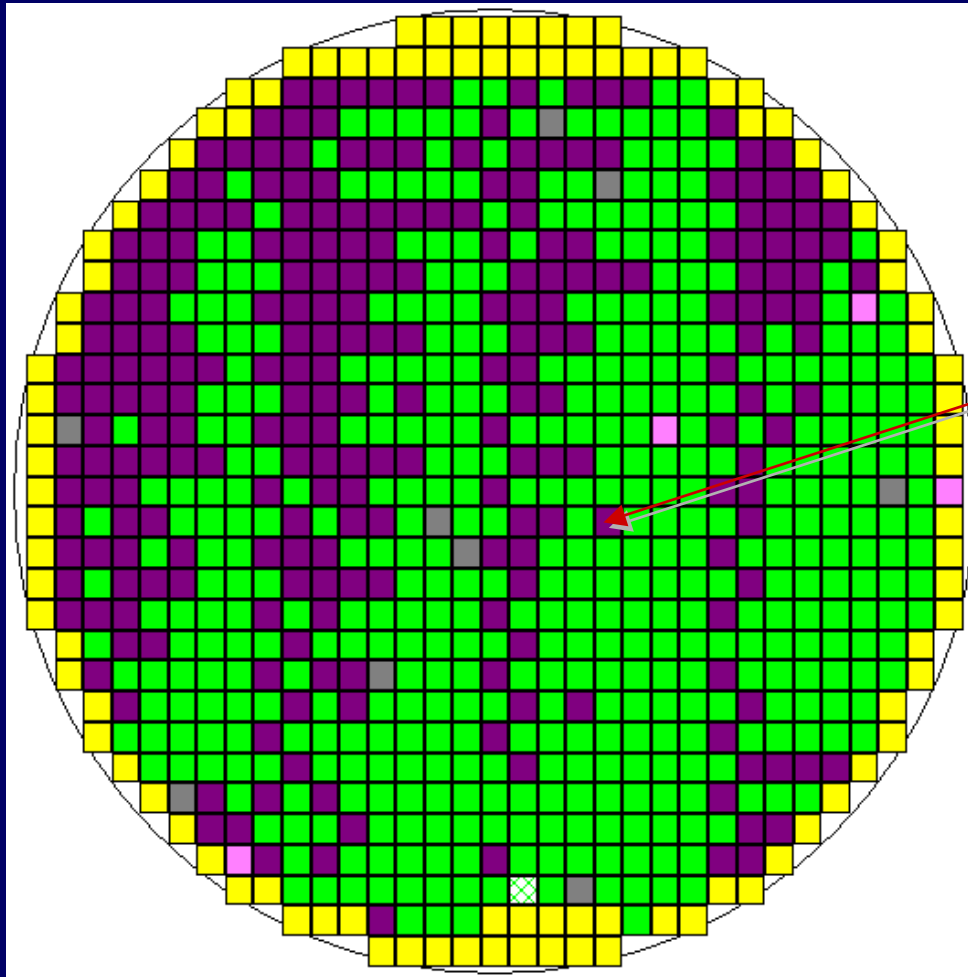
False "too big" defects from debris



 Probe "Too Big"

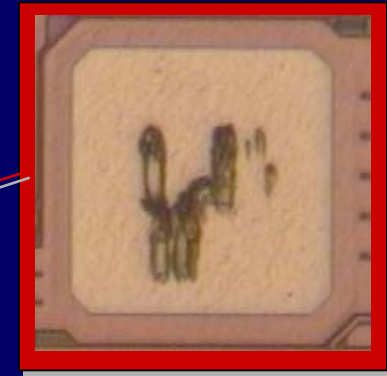
 Pass

Defect Map With Area Filter



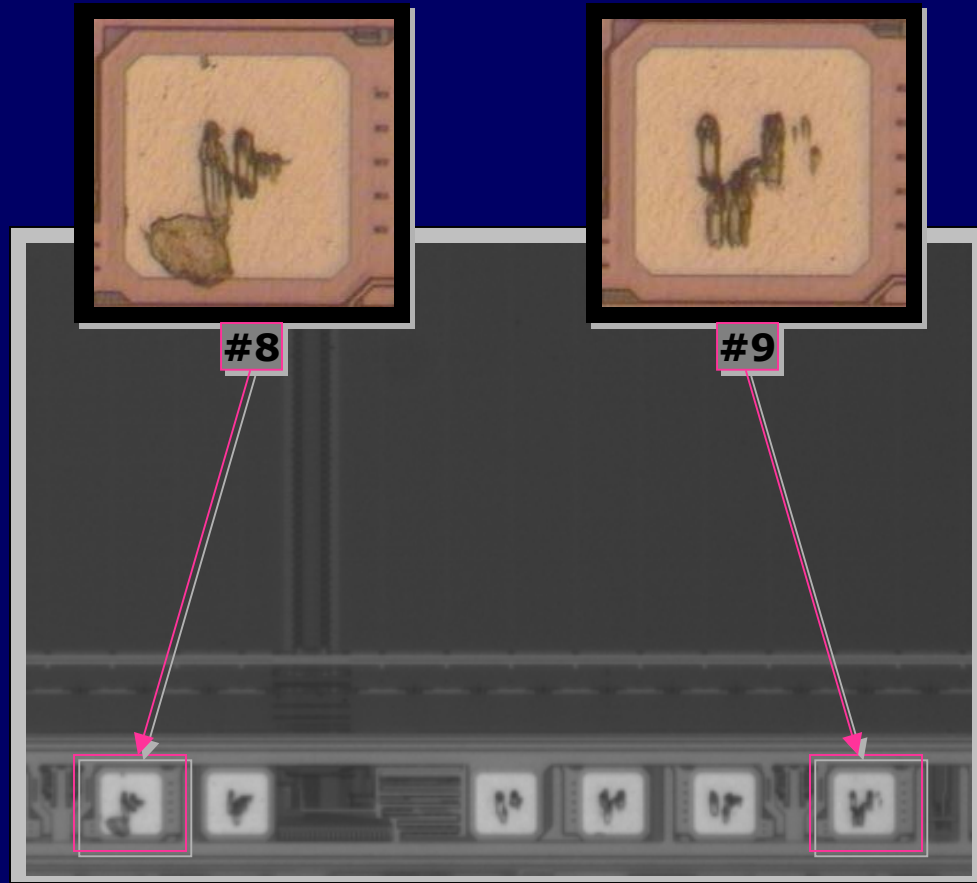
■ Probe "Too Big"

■ Pass



True "too big"
defect

Pad Areas Before & After Filter



Before Filter:

Pad #8 **FAILS**

Pad #9 **FAILS**

Measurement	Die	Area %	Area um square
6	0	23.203909	1409.305542
7	0	21.484575	1314.597412
8	0	28.773952	1746.843262
9	0	25.316364	1537.989868

After Filter:

Pad #8 **PASSES**

Pad #9 **FAILS**

Measurement	Die	Area %	Area um square
6	0	23.203909	1409.305542
7	0	21.484575	1314.597412
8	0	21.993752	1746.843262
9	0	25.316364	1537.989868

Statistical Probe Mark Area Filter

Advantages

- Easy to use – user only specifies filter threshold level
- Fast – filter does not reduce machine throughput
- Effective – debris which significantly increases the perceived probe damage area is automatically cleared
- Automatically adjusts to variability of probing process. A well controlled process will have a lower standard deviation, resulting in a tighter debris filter threshold

Disadvantages

- Not effective for small debris which does not significantly increase the probe damage area but does occlude the bond pad edge is not cleared and may cause false rejects
- May cause escapes if one probe needle creates a significantly larger damage area than other probe needles

Probe Mark Debris Filter – Edge Debris

Sample defect images



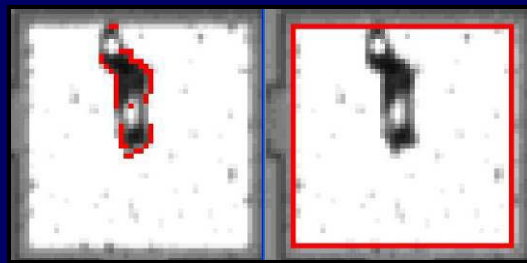
All three defects caught as probe position

Sample defect images cleared with edge debris filter algorithm

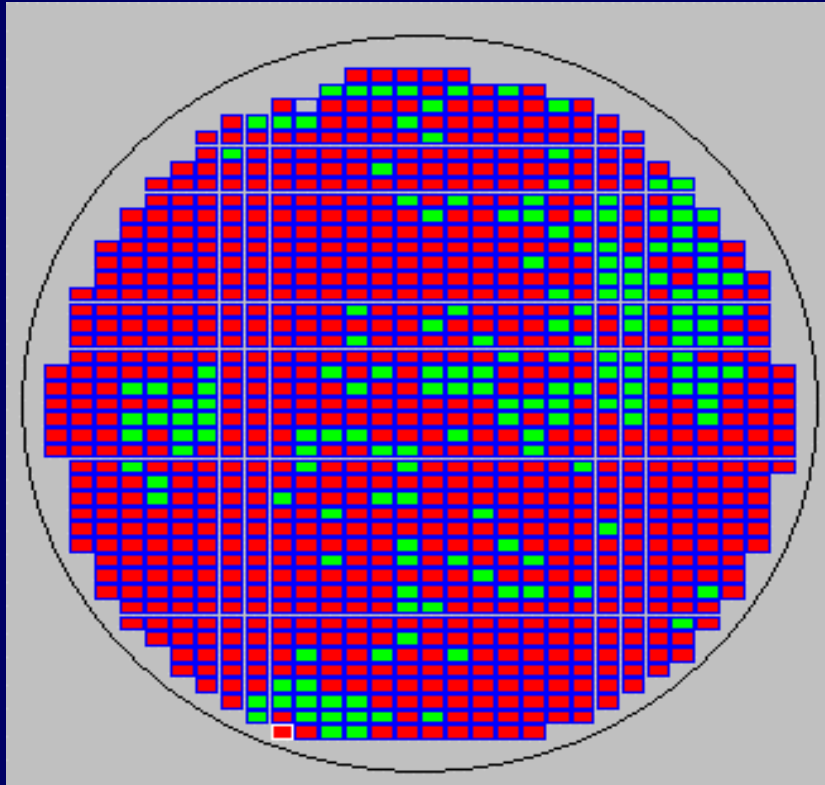


All three defects caught as probe position initially

Gradient analysis around the edge of the bond pad



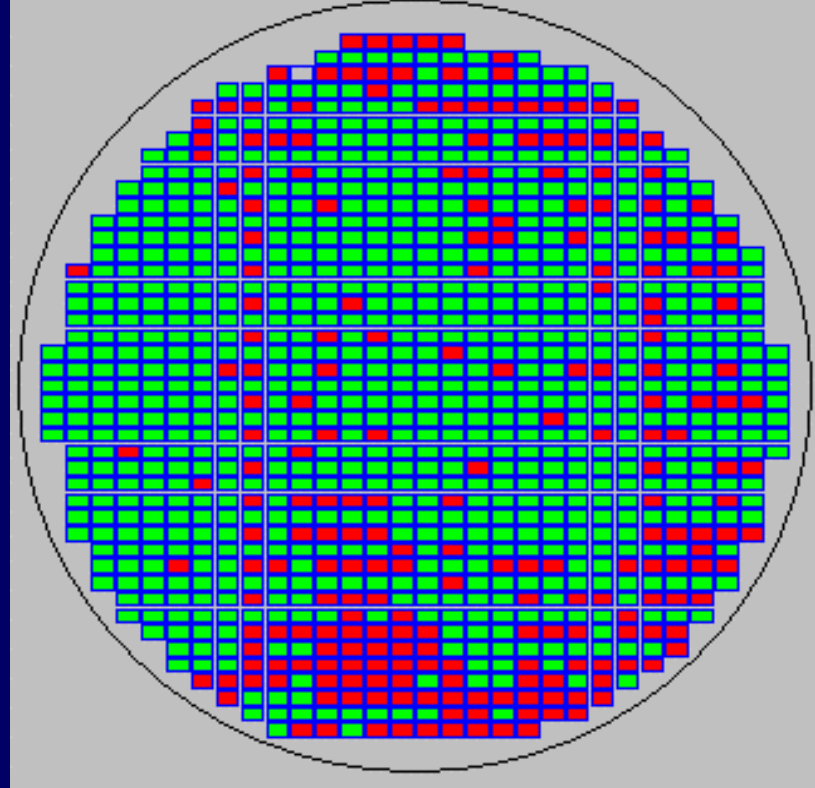
Method 1 – No Debris Filters



<i>Inspection Results:</i> <i>10x</i>	<i>Inspection Time:</i>	<i>10 minutes</i> <i>30 seconds</i>
	<i>Total number of defects:</i>	<i>7100</i>
	<i>Approximate Review Time:</i>	<i>1 hours 10 minutes</i>

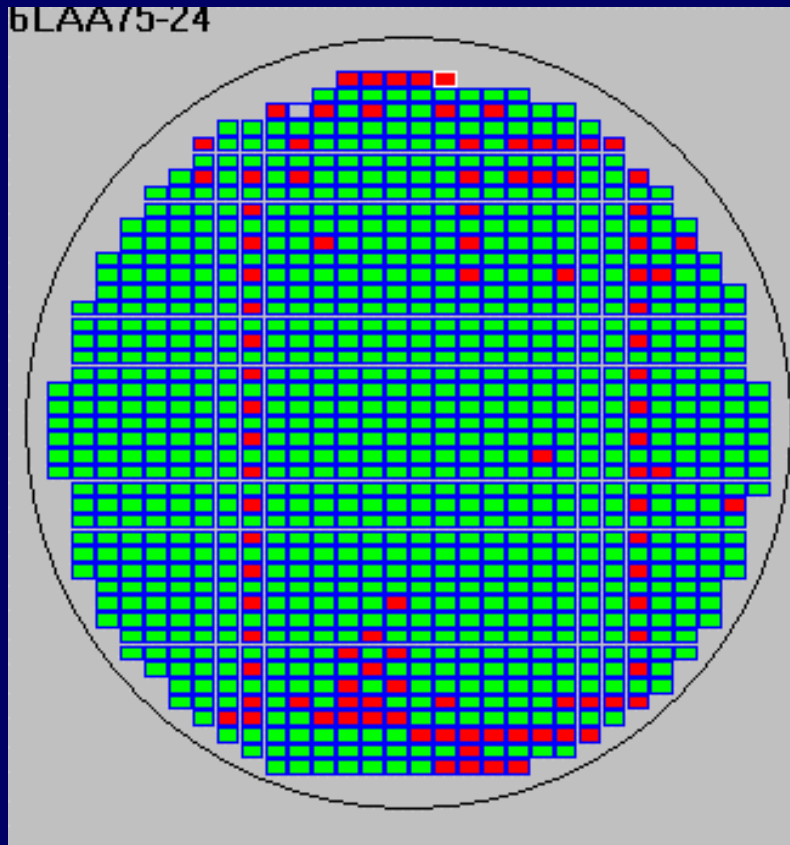
Method 2 – With Edge Debris Filter

5LAA75-24



Inspection Results: 5x	Inspection Time:	4 minutes 30 secs
	Total number of defects:	680
	Approximate Review Time:	7 minutes
Number of defects caught as probe position		279
Number of defects caught as edge defects		401

Manual Review of Defects



<i>Inspection Results:</i>	<i>Total number of defects left:</i>	300
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Edge Debris Filter

Advantages

- Fast – filter does not reduce system throughput
- Effective for small debris – debris which does not significantly increase the probe damage area, but does occlude the bond pad edge, is automatically cleared based on position variation
- Easy to setup – specify the width of edge analysis

Disadvantages

- Have not eliminated review – while the amount of review has been significantly reduced, a fair amount of review is still required

Summary of Debris Filter Usage

Type of Debris Filter	Cantiliver Probing	Vertical Probing/ Microspring
Size	Applicable	Not an issue
Edge Debris	Applicable	Not an issue

Acknowledgements

This data was generated by the following August Technology personnel:

- Woo Young Han
- Max Guest
- Steve Frankeberger



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Thank You